

Serial No.: 09/988,017

**REMARKS**

In response to the pending Office Action, Applicants have amended the specification so as to address the issues raised in the Office Action. It is believed that each of the formal matters, except those noted below, identified by the Examiner on pages 2-3 of the Office Action have been corrected by the foregoing amendments. Applicants wish to thank the Examiner for his assistance improving the clarity of the specification.

It is noted that the use of the term "damascene" was questioned. However, "damascene processes" are well known to those of skill in the art. Applicants have attached Abstracts of three US patents which utilize the term in question. Accordingly, as it is preferably to omit from specifications discussions regarding subject matter which is well known in the art, it is respectfully submitted there is no reason to amend the specification to contain a further description of damascene processes.

In addition, it was requested that page 17, line 25 and page 20, line 2 be amended to further clarify the reference to the "drawings". However, upon review of the specification, it is clear that the "drawings" referred to in these portions of the specification are identified in the subsequent paragraphs, and this fact is indicated in the specification. Accordingly, it is respectfully submitted that the current language is neither misleading nor inaccurate, and therefore, there is no need to make any further amendments thereto.

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Having fully responded to all matters raised in the Office Action, Applicants submit that all claims are in condition for allowance, an indication for which is respectfully solicited.

If there are any outstanding issues that might be resolved by an interview or an Examiner's amendment, the Examiner is requested to call Applicants' attorney at the telephone number shown below.

Respectfully submitted,

McDERMOTT, WILL &amp; EMERY

Date: 2/17/04By: 

Michael E. Fogarty  
Registration No. 36,139

600 13th Street, N.W., Suite 1200  
Washington, D.C. 20005-3096  
Telephone: 202-756-8000  
Facsimile: 202-756-8087  
WDC99 880436-1.043887.0168

United States Patent: 6,689,681

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United States Patent  
Watanabe

6,689,681  
February 10, 2004

Semiconductor device and a method of manufacturing the same

**Abstract**

A semiconductor device includes a first insulating layer which is formed above a semiconductor substrate including a plurality of semiconductor elements and which includes lower-layer damascene wiring, a second insulating layer which is formed on the first insulating layer and which includes a second damascene wiring and an aligning wiring pattern forming a first step, and a first aligning surface wiring pattern including a surface wiring pattern to cover the second damascene wiring and a first aligning surface wiring pattern which is formed on the aligning wiring pattern and which has a second step reflecting the first step. The surface wiring pattern and the first aligning surface wiring pattern are formed using one surface wiring layer. A novel multilayer wiring structure thus obtained is suitably manufactured by the *damascene process*.

Inventors: **Watanabe; Kenichi** (Kawasaki, JP)

Assignee: **Fujitsu Limited** (Kawasaki, JP)

Appl. No.: 242623

Filed: September 13, 2002

**Foreign Application Priority Data**

Apr 13, 2001[JP]

2001-115501

**Current U.S. Class:** 438/633; 438/638; 438/975; 257/E21.577; 257/E21.579

**Intern'l Class:** H01L 021/476.3

**Field of Search:** 438/587,622-633,637-638,618,975, FOR 435  
257/E21.577, E21.579, E23.152

**References Cited [Referenced By]**

**U.S. Patent Documents**

633519

Dec., 2001

Nakazawa.

United States Patent: 6,680,252

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United States Patent  
Chen , et al.

6,680,252  
January 20, 2004

Method for planarizing barc layer in dual damascene process

**Abstract**

The present invention is directed to a method for planarizing BARC layer in dual *damascene process*. For forming a dual damascene interconnect structure, by use of the present invention, a planar topography of the BARC layer is achieved by chemical mechanical polishing. The present invention applies a low temperature to bake the coated BARC layer before BARC material cross-links and induces the anti-reflective characteristic. Then, the BARC layer is planarized by chemical mechanical polishing. Next, a high temperature baking of the BARC layer is provided before coating the photoresist, so formation of the BARC layer is controlled with minimized variation in surface level and has the antireflective characteristic. Thus, the profile distortion on the via and the critical dimension control for the via are improved by patterning the via on a planar and an anti-reflective surface.

Inventors: **Chen; Anseime** (Hsin-Chu, TW); **Huang; Hui-Ling** (Hsin-Chu, TW); **Chang; Vencent** (Taipei, TW); **Chang; Andersen** (Miao-Li, TW)

Assignee: **United Microelectronics Corp.** (Hsin-Chu, TW)

Appl. No.: 854966

Filed: May 15, 2001

**Current U.S. Class:**

438/691; 438/692

**Intern'l Class:**

H01L 021/302

**Field of Search:**

438/700,690-693,720,723,724,725

**References Cited [Referenced By]****U.S. Patent Documents**

<u>3935330</u>	Jan., 1976	Smith et al.	427/487.
<u>5939236</u>	Aug., 1999	Pavelchek et al.	430/273.
<u>6187661</u>	Feb., 2001	Lou	438/622.
<u>6319821</u>	Nov., 2001	Liu et al.	438/636.

United States Patent: 6,686,643

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United States Patent  
Schwarzl, et al.

6,686,643  
February 3, 2004

Substrate with at least two metal structures deposited thereon, and method for fabricating the same

**Abstract**

Metal structures that can be produced by a *damascene process* are disposed in a first insulating layer and a second insulating layer is disposed above the latter. There is in each case at least one cavity which is disposed between the metal structures, is disposed in the first insulating layer and is covered by the second insulating layer. The cavities and the metal structures are produced next to one another by self-aligned process steps.

Inventors: Schwarzl; Siegfried (Neubiberg, DE); Pamler; Werner (Munich, DE); Gabric; Zvonimir (Zorneding, DE)

Assignee: Infineon Technologies AG (Munich, DE)

Appl. No.: 725346

Filed: November 29, 2000

**Foreign Application Priority Data**

Nov 29, 1999[DE]

199 57 302

Current U.S. Class:

257/522; 257/758

Intern'l Class:

H01L 029/00

Field of Search:

257/760,752,753,758,762,763,522

**References Cited [Referenced By]**

U.S. Patent Documents			
<u>5869880</u>	Feb., 1999	Grill et al.	257/522.
<u>5949143</u>	Sep., 1999	Bang	257/758.
<u>5994776</u>	Nov., 1999	Fang et al.	257/758.
<u>6211561</u>	Apr., 2001	Zhao	257/522.